

IN THE CLAIMS:

1. A microelectronic component assembly, comprising:

a substrate having at least one contact;

a motherboard having at least one contact;

D1 at least one solder ball extending between said at least one substrate contact and said at least one motherboard contact, wherein said at least one solder ball is attached to one of said at least one substrate contact and said at least one motherboard contact;

wherein said at least one of said at least one substrate contact and said at least one motherboard contact is recessed and has a semispherical surface which is substantially the same radius as a radius of said solder ball; and

a compression mechanism for imparting pressure between said substrate and said motherboard.

12. A microelectronic component assembly, comprising:

D2 a substrate having a first surface and a second surface, wherein said first substrate first surface includes at least one contact;

a motherboard having a first surface and a second surface; wherein said motherboard first surface includes at least one contact;

D2 at least one solder ball extending between said at least one substrate first surface contact and said at least one motherboard first surface contact, wherein said at least one solder ball is attached to one of said at least one substrate first surface contact and said at least one motherboard first surface contact;

wherein said at least one of said at least one substrate contact and at least one
D2 motherboard contact is recessed and has a semispherical surface which is substantially the same
radius as a radius of said solder ball; and
a support structure for imparting pressure between said substrate and said motherboard.

28. A substrate contact for forming a non-reflow electrical contact with a solder ball,
comprising:

D3 a recess defined in a substrate by at least one surface extending into said substrate; and
a conductive material layered over said recess forming a void therebetween, wherein said
conducting material forms a semispherical surface which substantially conforms to the surface of
said solder ball.

Please cancel claims 5/7 and 29-31, without prejudice